# Display Elektronik GmbH

# DATA SHEET

# **TFT MODULE**

# **DEE 172072A – W**

2,0" E-PAPER DISPLAY

**Product Specification** 

**Ver.: 3** 

DOCUMENT	DATE	DESCRIPTION	CHANGED	CHECKED
REVISION			BY	BY
0	30.03.2012	First Release.	LY	MH
1	15.10.2012	Items 1 were updated. The table 5 was updated.	LY	МН
2	12.09.2013	Items 1 were updated. The table 5 was updated.	LY	МН
3	24.12.2013	Items 1 to 2 were updated. The command table was updated.	LY	МН

# **CONTENTS**

		<u>Page No.</u>
1.	GENERAL DESCRIPTION	4
2.	MECHANICAL SPECIFICATIONS	4
3.	INTERFACE SIGNALS	7
4. 4.1	ABSOLUTE MAXIMUM RATINGS ELECTRICAL MAXIMUM RATINGS (Ta=25°C)	9 9
5.	ELECTRICAL SPECIFICATIONS	9
6.	COMMAND DESCRIPTION	25
7.	TYPICAL OPERATING SEQUENCE	31
8.	OPTICAL CHARACTERISTICS	36
9.	APPEARANCE INSPECTION STANDARD	37
10.	HANDLING, SAFETY AND ENVIRONMENTAL REQUIREMENTS	39
11.	RELIABILITY TEST	40

#### 1. General Description

DEE 172072A – W is an Active Matrix Electrophoretic Display (AMEPD), with interface and a reference system design. The 2.04" active area contains 172x72 pixels, and has 2-bit full display capabilities. The module is a TFT-array driving electrophoretic display, with integrated circuits including gate buffer, source buffer, MCU interface, timing control logic, oscillator, DC-DC, SRAM, LUT, VCOM. Module can be used in portable electronic devices, such as Electronic Shelf Label (ESL) System.

- ◆172×72 pixels display
- ♦ White reflectance above 30%
- ◆Contrast ratio above 7:1
- ◆Ultra wide viewing angle
- ◆Ultra low power consumption
- ◆Pure reflective mode
- ◆Bi-stable display
- ◆Commercial temperature range
- ◆Landscape, portrait modes
- ◆ Hard-coat antiglare display surface
- ◆Ultra Low current deep sleep mode
- ◆On chip display RAM
- ◆ Waveform stored in On-chip OTP
- ◆ Serial peripheral interface available
- ◆On-chip oscillator
- ◆On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- ◆I2C signal master interface to read extremely temperature sensor

#### 2. Mechanical Specifications

The mechanical detail is shown in Fig. 1 and summarized in Table 1 below.

Parameter	Specifications	Unit	Remark
Screen Size	2.04	Inch	-
Display Resolution	172 x 72 (or 72 x 172)	Pixel	dpi:95
Active Area	20.16 x 48.16 (or 48.16 x 21.16)	mm	-
Pixel Pitch	0.280 x 0.280	mm	-
Pixel Configuration	Rectangle	-	-
Outline Dimension	29.20 x 59.20 x 1.18 (or 59.20 x 29.20 x 1.18)	mm	-

NC   13   D0(SCLK)     NC   13   D0(SCLK)     2   GDR   14   D1(SDIN)     3   RESE   15   VDDIO     4   VGL   16   VCI     5   VGH   17   VSS     6   TSCL   18   VDD     7   TSDA   19   VPP     8   BSI   20   VSH     9   BUSY   21   PREVGH     10   RES   22   VSL     11   D/C   23   PREVGL     12   CS   24   VCOM	
(13.1)———————————————————————————————————	25 Pitch. 5 (6.25) -
BACK  Contact side  FRONT  (7.24)	Protective finance (CC ores)  Protective finance (CC ores)  Protective finance (CC ores)  RED THICKNESS  Section drowing  Scale: 2.5:1
3) 5.84 1.6(A.A) 49.56(EPL) 52.85(EPL) 51.76(PS) 6.0±0.5 54.97(PS) 14.1±0.5	ht:max 0.77mm)  th EC:max 1.33mm)  Graphic E-Paper+TFT LCD  DOTS: 172 x 72  / / / / / / / / / / / / / / / / / /
	Notes: 1.UV Despense (Height:max 0.77mm) 2.EPD thickness (With EC:max 1.33mm) Quotation No: Display Type Graphic E-Paper+TFT Display Resolution DOTS:172 x 72 Viewing Angle Max.Ratio and Bias Level Max.Ratio and Bias Level Logic Voltage EPD Driving Voltage TBD Operation Temperature Storage Temperature Storage Temperature Backlight Speciality No backlight

Figure 1: Module Specification

Kind suggestion: VA of customer's application should be 0.5mm smaller than LCD VA in each side.

1.18 -0.70(Glass)

—29.20(Outline)—24.36(PS)—22.16(EPL)—20.16(A.A)—(10.08)

(3.0) (2.3)-

Version: 3

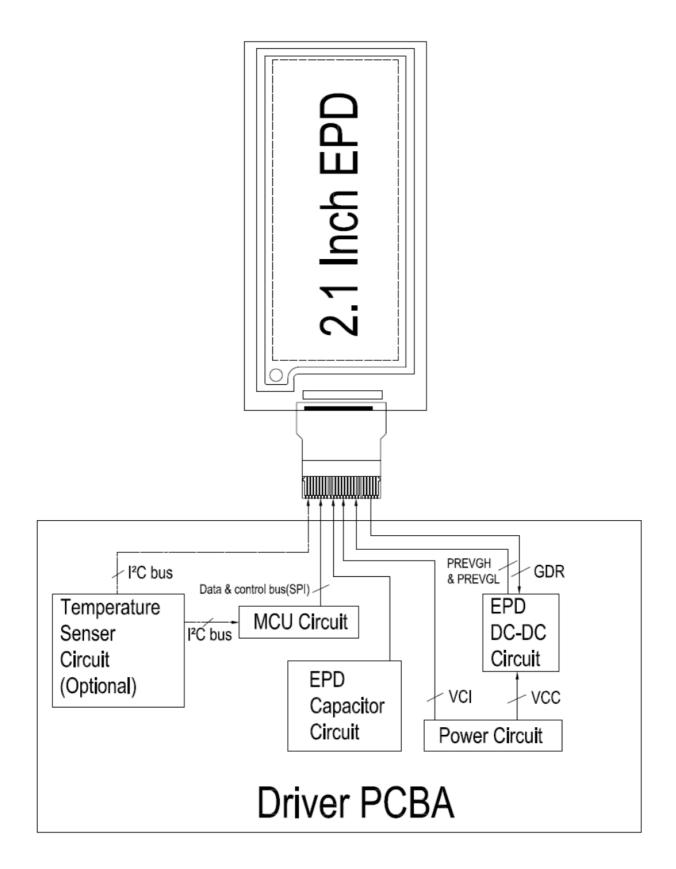


Figure 2: Block Diagram

## 3. Interface Signals

Pin #	Type	Single	Description	Remark
1	-	NC	Do not connect with other NC pins	Keep Open
2	О	GDR	N-Channel MOSFET Gate Drive Control	-
3	О	RESE	Current Sense Input for the Control Loop	-
4	C	VGL	Negative Gate driving voltage	1
5	C	VGH	Positive Gate driving voltage	1
6	О	TSCL	I2C Interface to digital temperature sensor Clock pin	-
7	I/O	TSDA	I2C Interface to digital temperature sensor Data pin	-
8	I	BS1	Bus selection pin	Note 5
9	О	BUSY	Busy state output pin	Note 4
10	I	RES#	Reset	Note 3
11	I	D/C #	Data /Command control pin	Note 2
12	I	CS#	Chip Select input pin	Note 1
13	I/O	D0	serial clock pin (SPI)	•
14	I/O	D1	serial data pin (SPI)	1
15	C	VDDIO	Power for I/O logic pins. Connect to VCI.	1
16	I	VCI	Power Supply pin for the display driver chip	1
17	I	VSS	Ground	-
18	C	VDD	Main logic power supply pin	1
19	C	VPP	Power Supply for OTP Programming	ı
20	C	VSH	Positive Source driving voltage	1
21	С	PREVGH	Power Supply pin for VGH and VSH	-
22	C	VSL	Negative Source driving voltage	-
23	C	PREVGL	Power Supply pin for VCOM, VGL and VSL	-
24	C	VCOM	VCOM driving voltage	-

Note 1: This pin is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW in parallel interface. When CS# is not in use, please connect to VCI or VSS.

Note 2: This pin is Data/Command control pin connecting to the MCU. When the pin is pulled HIGH, the data at [7:0] will be interpreted as data. When the pin is pulled LOW, the data at D[7:0] will be interpreted as command.

Note 3: This pin is reset signal input. Active Low.

Note 4: This pin is busy state output pin. When Busy is High, the operation of chip should not be interrupted, command should not be sent. e.g., The chip would put Busy pin High when

- Outputting display waveform; or
- Programming with OTP
- Communicating with digital temperature sensor

Note 5: Table: Bus interface selection

BS1	MPU Interface
L	4-lines serial peripheral
	interface (SPI)
Н	3-lines serial peripheral
	interface (SPI) - 9 bits SPI

# 4. Absolute Maximum Ratings

# 4.1 Electrical Maximum Ratings (Ta = 25 °C)

Parameter	Symbol	Rating	Unit
Logic Supply Voltage	VCI	-0.5 to +3.6	V
Logic Input Voltage	VIN	-0.5 to VCI +0.5	V
Logic Output Voltage	VOUT	-0.5 to VCI +0.5	V
Operating Temp. Range	TOPR	0 to +50	°C
Storage Temp. Range	TSTG	-25 to +70	°C

## 5. Electrical Specifications

#### **5.1 Panel DC Characteristics**

The following specifications apply for: VSS = 0V, VCI = 3.0V, TA =  $25\Box$ 

Parameter	Symbol	Condition	Applicable pin	Min.	Тур.	Max.	Unit
Single ground	VSS		-	-	0	-	V
Maximum image update Time at 25°C	-		-	-	1800	-	ms
Logic supply voltage	VCI	-	VCI	2.4	3.0	3.3	V
High level input voltage	VIH	-	-	0.8 VCI	-	-	V
Low level input voltage	VIL	-	-	-	-	0.2 VCI	V
High level output voltage	VOH	IOH = -100uA	-	0.9 VCI	ı	ı	V
Low level output voltage	VOL	IOL = 100uA	-	-	-	0.1 VCI	V
OTP Program voltage	VPP	-	VPP	-	7.5	-	V
Typical power panel	PTYP	-	-	-	24	36	mW
Standby power panel	PSTPY	-	-	-	0.006	-	mW
Typical operating current	Iopr_VCI	-	-	-	8.0	-	mA
Sleep mode current  Deep sleep mode current	Islp_VCI Idslp_VCI	VCI=3.3V DC/DC OFF No clock No output load Ram data retain VCI=3.3V DC/DC OFF No clock No output load Ram data not retain	VCI	-	2	50	uA uA
Operation temperature range	TOPR	1	-	0	-	50	°C
Storage temperature range	TSTG	-	-	-20	-	70	°C

#### Notes:

- 1. The typical operating current is measured with following transition: from horizontal 4 gray scale pattern to vertical 4 gray scale pattern.
- 2. The standby power is the consumed power when the panel controller is in standby mode.
- 3. The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by DISPLAY.

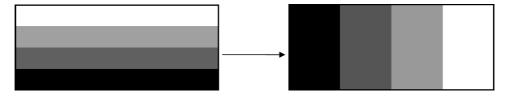


Figure: The typical power consumption measure pattern

# **5.2 Panel DC Characteristics (Driver IC Internal Regulators)**

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =25°C.

Parameter	Symbol	Condition	Applicable pin	Min.	Тур.	Max.	Unit
VDD operation voltage	VDD	-	VDD	1.7	1.8	1.9	V
VCOM output voltage	VCOM	-	VCOM	-4.0	-	+0.2	V
Gate output voltage	VGATE	-	G0-171	-20	-	+22	V
Gate output peak to peak voltage	VGATE(p-p)	-	G0-171	1	1	42	V
Positive Source output voltage	VSH	-	S0-71	+10	ı	+17	V
Negative Source output voltage	VSL	-	S0-71	ı	-VSH	-	V

#### **5.3 Panel AC Characteristics**

#### **5.3.1 MCU Interface Selection**

MCU interface consist of 2 data/command pins and 3 control pins. The pin assignment at different interface mode is summarized in Table. Different MCU mode can be set by hardware selection on BS1 pins. The display panel only supports 4-wire SPI or 3-wire SPI interface mode.

## MCU interface assignment under different bus interface mode

Pin Name	Data/Connn	and Interface	Control Signal		
Bus interface	D1	D0	CS#	D/C#	RES#
4-wire SPI	SDIN	SCLK	CS#	D/C#	RES#
3-wire SPI	SDIN	SCLK	CS#	L	RES#

#### 5.3.2 MCU Serial Interface (4-wire SPI)

The serial interface consists of serial clock SCLK, serial data SDIN, D/C#, CS#. In 4-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN.

#### Control pins of 4-wire Serial interface

Function	CS#	D/C#	SCLK
Write command	L	L	1
Write data	L	Н	<b>↑</b>

Note: ↑ stands for rising edge of signal

SDIN is shifted into an 8-bit shift register on every rising edge of SCLK in the order of D7, D6, ... D0.

D/C# is sampled on every eighth clock and the data byte in the shift register is written to the Graphic Display Data RAM (RAM) or command register in the same clock.

Under serial mode, only write operations are allowed.

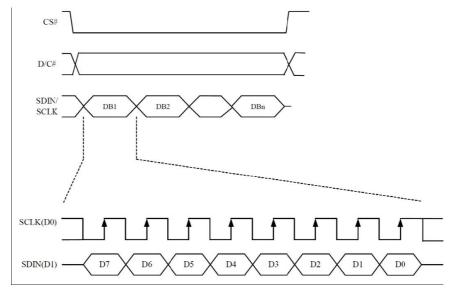


Figure: Write procedure in 4-wire SPI mode

#### 5.3.3 MCU Serial Interface (3-wire SPI)

The 3-wire serial interface consists of serial clock SCLK, serial data SDIN and CS#. In 3-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN.

The operation is similar to 4-wire serial interface while D/C# pin is not used. There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence: D/C# bit, D7 to D0 bit. The D/C# bit (first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0). Under serial mode, only write operations are allowed.

Control pins of 3-wire Serial interface

Function	CS#	D/C#	SCLK
Write command	L	Tie	<b>↑</b>
Write data	L	Tie	<b>↑</b>

Note: ↑ stands for rising edge of signal

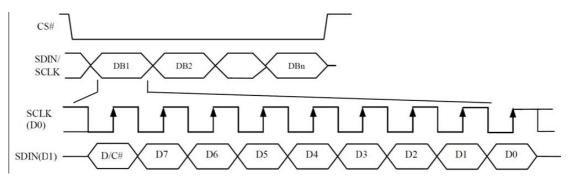


Figure: Write procedure in 3-wire SPI mode

# **5.3.4 Interface Timing**

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =25°C.

Symbol	Parameter	Test Condition	Applicable pin	Min.	Тур.	Max.	Unit
Fosc	Internal Oscillator frequency	VCI=2.4 to 3.3V	CL	0.95	1	1.05	MHz

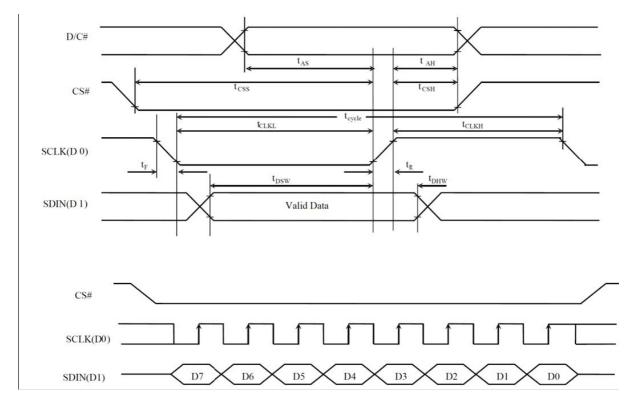


Figure: Serial interface characteristics

 $(V_{CI} - VSS = 2.4V \text{ to } 3.3V, T_{OPR} = 25^{\circ}C, CL = 20pF)$ 

**Table: Serial Interface Timing Characteristics** 

Symbol	Parameter	Min.	Typ.	Max.	Unit
tcycle	Clock Cycle Time	250	1	-	ns
tAS	Address Setup Time	150	-	-	ns
tAH	Address Hold Time	150	-	-	ns
tCSS	Chip Select Setup Time	120	-	-	ns
tCSH	Chip Select Hold Time	60	-	-	ns
tDSW	Write Data Setup Time	50	-	-	ns
tDHW	Write Data Hold Time	15	-	-	ns
tCLKL	Clock Low Time	100	-	-	ns
tCLKH	Clock High Time	100	1	-	ns
tR	Rise Time [20% ~ 80%]	-	1	15	ns
tF	Fall Time [20% ~80%]	-	-	15	ns

# **5.4 Command Table**

Func	lame	ntal	Com	man	d Tal	ole						
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
1	0	7	0	0	0	0	0	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	Status Read	Read Driver status on
0	0	01	0	0	0	0	0	0	0	1	Driver Output control	Gate setting
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>		A[7:0]: MUX setting as A[7:0] + 1 POR = B3h + 1 MUX
0	1		0	0	0	0	0	B <sub>2</sub>	B₁	B <sub>o</sub>		B[2:0]: Gate scanning sequence and direction
												B[2]: GD Selects the 1st output Gate GD='0', G0 is the 1st gate output channel, gate output sequence is G0,G1, G2, G3, [POR] GD='1', G1 is the 1st gate output channel, gate output sequence is G1, G0, G3, G2,
												B[1]: SM Change scanning order of gate driver. SM=0, G0, G1, G2, G3G179 (left and right gate interlaced) [POR] SM=1, G0, G2, G4G178, G1, G3,G179  B[0]: TB
												TB = 0, scan from G0 to G179 [POR] TB = 1, scan from G179 to G0
0	0	02	0	0	0	0	0	0	1	0	Reserve	
0	0	03	0	0	0	0	0	0	1	1	Gate Driving voltage	Set Gate related driving voltage
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	<b>A</b> <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	Control	A[7:4]: VGH, 15 to 22V in 0.5V step

	lame					D4	D3	D2	D1	DO	Command	Description
	D/C#		D7	D6	D5	D4	D3	D2	D1	DO	Command	VGH
0	0	04	0	0	0	0	0	1	0	0	Source Driving voltage Control	Others N/A Set Source output voltage magnitude
0	1		0	0	0	0	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	Ao	Voltage Control	A[3:0]: VSH/VSL 10V to 17V in 0.5V step
												VSH/VSL  0000 10.0  0001 10.5  0010 11.0  0011 11.5  0100 12.0  0101 12.5  0110 13.0  0111 13.5  1000 14.0  1001 14.5  1010 15.0 [POR]  1011 15.5  1100 16.0  1101 16.5  1110 17.0
				l		l .						Others N/A

Func	lame	ntal	Com	man	d Tal	ole						
	D/C#		D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	Ao	position	gate driver. The valid range is from 0 to 179. TB=0: SCN [7:0] = A[7:0]
0	0	10	0	0	0	1	0	0	0	0	Deep Sleep mode	Deep Sleep mode Control
0	1		0	0	0	0	0	0	0	A <sub>0</sub>		A[0] :         Description           0         [POR]           1         Enter Deep Sleep Mode
0	0	11	0	0	0	1	0	0	0	1	Data Entry mode	Define data entry sequence
0	1	12	0	0	0	0	0	A <sub>2</sub>	Aı	Ao	setting	A [1:0]: Address automatic increment / decrement setting The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address.  00 —Y decrement, X decrement, 01 —Y decrement, X increment, 10 —Y increment, X decrement, 11 —Y increment, X increment [POR]  A[2]: Set the direction in which the address counter is updated automatically after data are written to the RAM.  A[2] = 0, the address counter is updated in the X direction. [POR]  A[2] = 1, the address counter is updated in the Y direction.
0	0	12	0	0	0	1	0	0	1	0	SWRESET	It resets the commands and parameters to their S/W Reset default values except R10h-Deep Sleep Mode Note: RAM are unaffected by this command
0	0	13	0	0	0	1	0	0	1	1	Reserve	
0	0	14	0	0	0	1	0	1	0	0	Reserve	
0	0	15	0	0	0	1	0	1	0	1	Reserve	
0	0	16	0	0	0	1	0	1	1	0	Reserve	
0	0	17	0	0	0	1	0	1	1	1	Reserve	
0	0	18	0	0	0	1	1	0	0	1	Reserve Reserve	
0	0	1A	0	0	0	1	1	0	1	0	Temperature Sensor	Write to temperature register.
0	1	1/	A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>o</sub>	Control (Write to	Write to temperature register.
0	1		B <sub>7</sub>	B <sub>6</sub>	B <sub>5</sub>	B <sub>4</sub>	0	0	0	0	temperature register)	A[7:0] – MSByte 01111111[POR] B[7:0] – LSByte 11110000[POR]
0	0	1B	0 X <sub>7</sub>	0 X <sub>6</sub>	0 X <sub>5</sub>	1 X <sub>4</sub>	1 X <sub>3</sub>	1 X <sub>2</sub>	0 X <sub>1</sub>	1 X <sub>0</sub>	Temperature Sensor Control (Read from	Read from temperature register. X[7:0] – MSByte

Note:If the module enter deep sleep mode, it must execute hardware RESET function to exit the deep sleep mode.

Func	lame	ntal	Com	mano	d Tak	ole						
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
1	1		<b>Y</b> <sub>7</sub>	Y <sub>6</sub>	<b>Y</b> <sub>5</sub>	Y <sub>4</sub>	0	0	0	0	temperature register)	Y[7:4] – LSByte
0	0	1C	0	0	0	1	1	1	0	0	Temperature Sensor	Write Command to temperature sensor
0	1		$A_7$	$A_6$	$A_5$	$A_4$	$A_3$	$A_2$	$A_1$	$A_0$	Control (Write	ACT.C1 Calant no of historia has cont
0	1		B <sub>7</sub>	B <sub>6</sub>	B <sub>5</sub>	B <sub>4</sub>	B <sub>3</sub>	$B_2$	B <sub>1</sub>	B <sub>0</sub>	Command to temperature sensor	A[7:6] – Select no of byte to be sent 00 – Address + pointer
0	1		$C_7$	C <sub>6</sub>	<b>C</b> <sub>5</sub>	$C_4$	$C_3$	$C_2$	$C_1$	$C_0$	)	01 – Address + pointer + 1 <sup>st</sup> parameter
												10 – Address + pointer + 1 <sup>st</sup> parameter
												+ 2 <sup>nd</sup> pointer
												11 - Address
												A[5:0] – Pointer Setting
												B[7:0] – 1 <sup>st</sup> parameter C[7:0] – 2 <sup>nd</sup> parameter
												C[7:0] – 2 parameter
												The command required CLKEN=1.
0	0	1D	0	0	0	1	1	1	0	1	Temperature Sensor	Load temperature register with
											Control (Load	temperature sensor reading
											temperature register with temperature	BUSY=H for whole loading period
											sensor reading)	The command required CLKEN=1.
												·
0	0	1E	0	0	0	1	1	1	1	0	Reserve	
0	0	1F	0	0	0	1	1	1	1	1	Reserve	
0	0	20	0	0	1	0	0	0	0	0	Master Activation	Activate Display Update Sequence
												The Display Update Sequence Option is
												located at R22h
												User should not interrupt this operation
					4			_		4	Discriss the data	to avoid corruption of panel images.
0	0	21	0	0	1	0	0	0	0	1	Display Update	Option for Display Update

Fund	dame	ntal	Com	man	d Tal	ole						
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	1		A <sub>7</sub>	0	A <sub>5</sub>	A4	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	Ao	Control 1	Bypass Option used for Pattern Display, which is used for display the RAM content into the Display  OLD RAM Bypass option A [7] 1
												GSC GSD A[3:2] A[1:0]  0000 GS0 GS0  0001 GS0 GS1  0010 GS0 GS2  0011 GS0 GS3 [POR]  0100 GS1 GS0  0101 GS1 GS1  0110 GS1 GS2  0111 GS1 GS3  1000 GS2 GS0  1001 GS2 GS1  1010 GS2 GS1  1010 GS2 GS2  1011 GS3 GS1  1100 GS3 GS0  1101 GS3 GS1  1110 GS3 GS2
_		20	_	_	4	_	_	_	-	_	Display Hadata	
0	0	22	0	0	1	0	0	0	1	0	Display Update	Display Update Sequence Option:

	D/C#		Com D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	1	IICA	A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	Ao	Control 2	Enable the stage for Master Activation
												Parameter (in Hex)
												Enable Clock Signal, Then Enable CP Then Load Temperature value Then Load LUT Then INIITIAL DISPLAY Then PATTERN DISPLAY Then Disable CP Then Disable OSC
												Enable Clock Signal, Then Enable CP Then Load Temperature value Then Load LUT Then PATTERN DISPLAY Then Disable CP Then Disable OSC
												To Enable Clock Signal 80 (CLKEN=1)
												To Enable Clock Signal, then Enable CP C0 (CLKEN=1, CPEN=1)
												To INITIAL DISPLAY + PATTEN OC
												To INITIAL DISPLAY 08
												To DISPLAY PATTEN 04
												To Disable CP, then Disable Clock Signal 03 (CLKEN=1, CPEN=1)
												To Disable Clock Signal (CLKEN=1) 01
										z.		Remark: CLKEN=1: If CLS=VDDIO then Enable OSC If CLS=VSS then Enable External Clo CLKEN=0: If CLS=VDDIO then Disable OSC AND INTERNAL CLOCK Signal = VSS,
0	0	23	0	0	1	0	0	0	1	1	Reserve	
0	0	24	0	0	1	0	0	1	0	0	Write RAM	After this command, data entries will written into the RAM until another command is written. Address pointers will advance accordingly.
0	0	25	0	0	1	0	0	1	0	1	Read RAM	After this command, data read on the MCU bus will fetch data from RAM, u another command is written. Address pointers will advance accordingly.
0	0	26	0	0	1	0	0	1	1	0	Reserve	
0	0	27	0	0	1	0	0	1	1	1	Reserve	

Func	lame	ntal	Com	man	d Tal	ole						
	D/C#		D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	28	0	0	1	0	1	0	0	0	VCOM Sense	Enter VCOM sensing conditions and hold for duration defined in 29h before reading VCOM value. The sensed VCOM voltage is stored in register The command required CLKEN=1.
0	0	29	0	0	1	0	1	0	0	1	VCOM Sense	Stabling time between entering VCOM
0	1		0	0	0	0	A <sub>3</sub>	Az	Aı	Ao	Duration	sensing mode and reading acquired. VCOM sense duration = Setting + 1 Seconds 0x09(10Seconds) [POR]
0	0	2A	0	0	1	0	1	0	1	0	Program VCOM OTP	Program VCOM register into OTP
0	0	2B	0	0	1	0	1	0	1	1	Reserve	
0	0	2C	0	0	1	0	1	0	1	1	Write VCOM register	Write VCOM register from MCU
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>		interface
0	0	2D	0	0	1	0	1	1	0	1	Read OTP Registers	Read register reading to MCU
1	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>		A [7:0] Spare OTP Option B [7:0] VCOM Register
1	1		B <sub>7</sub>	B <sub>6</sub>	B <sub>5</sub>	B <sub>4</sub>	B <sub>3</sub>	B <sub>2</sub>	B <sub>1</sub>	B <sub>0</sub>		B [r.o] VOOW Register
0	0	2E	0	0	1	0	1	1	1	0	Reserve	
0	0	2F	0	0	1	0	1	1	1	1	Reserve	
0	0	30	0	0	1	1	0	0	0	0	Program WS OTP	Program OTP of Waveform Setting The contents should be written into RAM before sending this command.
0	0	31	0	0	1	1	0	0	0	1	Reserve	
0	0	32	0	0	1	1	0	0	1	0	Write LUT register	Write LUT register from MCU [720 bits]
0	1										200	
0	1					LU	JT					
						[90 b						
0	1											
0	0	33	0	0	1	1	0	0	1	1	Read LUT register	Read from LUT register (excluding
1	1	-	-					U			Trodu 201 regioter	temperature data) [720 bits]
1	1											
1	1					L( [90 b						
1	1					โลก ก	ytes]					
1	1											
0	0	34	0	0	1	1	0	1	0	0	Reserve	
0	0	35	0	0	1	1	0	1	0	1	Reserve	
0	0	36	0	0	1	1	0	1	1	0	Program OTP selection	Program OTP Selection according to the OTP Selection Control [R36h]
0	0	37	0	0	1	1	0	1	1	1	OTP selection	Write the OTP Selection:

k/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description	n
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	Control		
١			. 4	, 40	7.5	. 4	, ,	2	2.41	′ °		A[7]=1	spare VCOM OTP
												A[6]	VCOM_Status
												A[5]=1	spare WS OTP
												A[4]	WS_Status
													reserved OTP bit. User can ts as Version Control.
												100000000000000000000000000000000000000	HEROTORU CHARLEST AND OF SE
0	0	38	0	0	1	1	1	0	0	0	Reserve		
0	0	39	0	0	1	1	1	0	0	1	Reserve		
0	0	3A	0	0	1	1	1	0	1	0	Set dummy line	Set numbe	r of dummy line period
0	1		0	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	period		mber of dummy line period in
												term of TG	ate
												4 [POR]	etting 0 to 127.
0	0	3B	0	0	1	1	1	0	1	1	Set Gate line width	_	ne width (TGate)
0	1	SD	0	0	0	0				1 11	Set Gate line width		width in us
۱	-		U	U	U	0	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>		[0.0]	
												0000	60
												0001	64
												0010	68
												0011	72
												0100	78
												0101	84
												0110	90
												0111	98
												1000	108 [POR]
												1001	120
												1010	136
												1011	154
												1100	180
												1101	216
												1110	272
												1111	362
													efault value will give 50Hz juency under 4 dummy line ng.
0	0	3C	0	0	1	1	1	1	0	0	Border Waveform	Select bord	der waveform for VBD

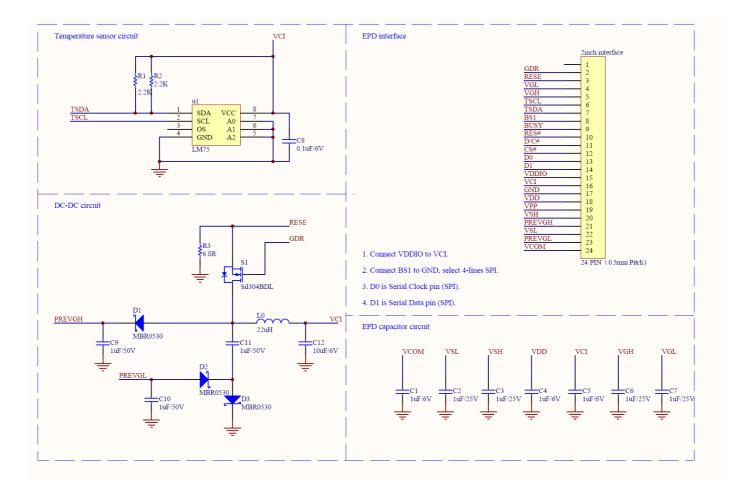
unc w#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
<b>w#</b> 0	1	Hex	D7 A7	D6 A6	D5 A5	D4 A <sub>4</sub>	D3 A3	<b>D2</b> A <sub>2</sub>	D1 A1	DO Ao	Control	Description
0	0	3D	0	0	1	1	1	1	0	1	Reserve	1111 GS3 GS3
0	0	3E	0	0	1	1	1	1	1	0	Reserve	1
0	0	3F	0	0	1	1	1	1	1	1	Reserve	
0	0	40	0	1	0	0	0	0	0	0	Reserve	
	0	41	0	1	0	0	0	0	0	1	Reserve	
)	0	42	0	1	0	0	0	0	1	0	Reserve	
0	0	43	0	1	0	0	0	0	1	1	Reserve	
]			-		-	~	_	-		1.00		
,	0	44	0	1	0	0	0	1	0	0	Set RAM X - address	s Specify the start/end positions of the

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	1		0	0	0	B <sub>4</sub>	B <sub>3</sub>	B <sub>2</sub>	B <sub>1</sub>	B <sub>0</sub>		address unit A[7:0]: XStart, POR = 00h B[7:0]: XEnd, POR = 1Fh
0	0	45	0	1	0	0	0	1	0	1	Set Ram Y- address	Specify the start/end positions of the
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	Start / End position	window address in the Y direction by an
0	1		B <sub>7</sub>	B <sub>6</sub>	B <sub>5</sub>	B <sub>4</sub>	Вз	B <sub>2</sub>	B <sub>1</sub>	Bo		address unit A[7:0]: YStart, POR = 00h B[7:0]: YEnd, POR = B3h
0	0	46	0	1	0	0	0	1	1	0	Reserve	
0	0	47	0	1	0	0	0	1	1	1	Reserve	
0	0	48	0	1	0	0	1	0	0	0	Reserve	
0	0	49	0	1	0	0	1	0	0	1	Reserve	
0	0	4A	0	1	0	0	1	0	1	0	Reserve	
0	0	4B	0	1	0	0	1	0	1	1	Reserve	
0	0	4C	0	1	0	0	1	1	0	0	Reserve	
0	0	4D	0	1	0	0	1	1	0	1	Reserve	
0	0	4E	0	1	0	0	1	1	1	0	Set RAM X address	Make initial settings for the RAM X
0	1		0	0	0	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	counter	address in the address counter (AC) POR is 0
0	0	4F	0	1	0	0	1	1	1	1	Set RAM Y address	Make initial settings for the RAM Y
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	counter	address in the address counter (AC) POR is 0
0	0	FO	1	1	1	1	0	0	0	0	Booster Feedback	Set Booster Feedback selection
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	Selection	0x1F = Internal Feedback is used POR is 0x1F
0	1	FF	1	1	1	1	1	1	1	1	NOP	This command is an empty command; it does not have any effect on the display module.  However it can be used to terminate Frame Memory Write or Read Commands.

# **5.5 Power Consumption**

Parameter	Symbol	Conditions	TYP	Max	Unit	Remark
Panel power consumption during update	-	-	0.657	3.610	mW	-
Power consumption in standby mode	-	-	-	TBD	mW	-

## **5.6 Reference Circuit**



# 6. Command Description

#### 6.1 Driver Output Control (01h)

This double byte command has multiple configurations and each bit setting is described as follows:

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	MUX7	MUX6	MUX5	MUX4	MUX3	MUX2	MUX1	MUX0
PC	)R	1	0	1	1	0	0	1	1
W	1						GD	SM	TB
PC	)R						0	0	0

**MUX[7:0]:** Specify number of lines for the driver: MUX[7:0] + 1. Multiplex ratio (MUX ratio) from 16 MUX to 180MUX.

**GD:** Selects the 1st output Gate This bit is made to match the GATE layout connection on the panel. It defines the first scanning line.

**SM:** Change scanning order of gate driver.

When SM is set to 0, left and right interlaced is performed.

When SM is set to 1, no splitting odd / even of the GATE signal is performed, Output pin assignment sequence is shown as below (for 180 MUX ratio):

	SM=0	SM=0	SM=1	SM=1
Driver	GD=0	GD=1	GD=0	GD=1
G0	ROW0	ROW1	ROW0	ROW90
G1	ROW1	ROW0	ROW90	ROW0
G2	ROW2	ROW3	ROW1	ROW91
G3	ROW3	ROW2	ROW91	ROW1
:	:	:	:	:
G88	ROW88	ROW89	ROW44	ROW134
G89	ROW89	ROW88	ROW134	ROW44
G90	ROW90	ROW91	ROW45	ROW135
G91	ROW91	ROW90	ROW135	ROW45
:	:	:	:	:
G176	ROW176	ROW177	ROW88	ROW178
G177	ROW177	ROW176	ROW178	ROW88
G178	ROW178	ROW179	ROW89	ROW179
G179	ROW179	ROW178	ROW179	ROW89

See "Scan Mode Setting" on next page.

**TB:** Change scanning direction of gate driver.

This bit defines the scanning direction of the gate for flexible layout of signals in module either from up to down (TB=0) or from bottom to up (TB=1).

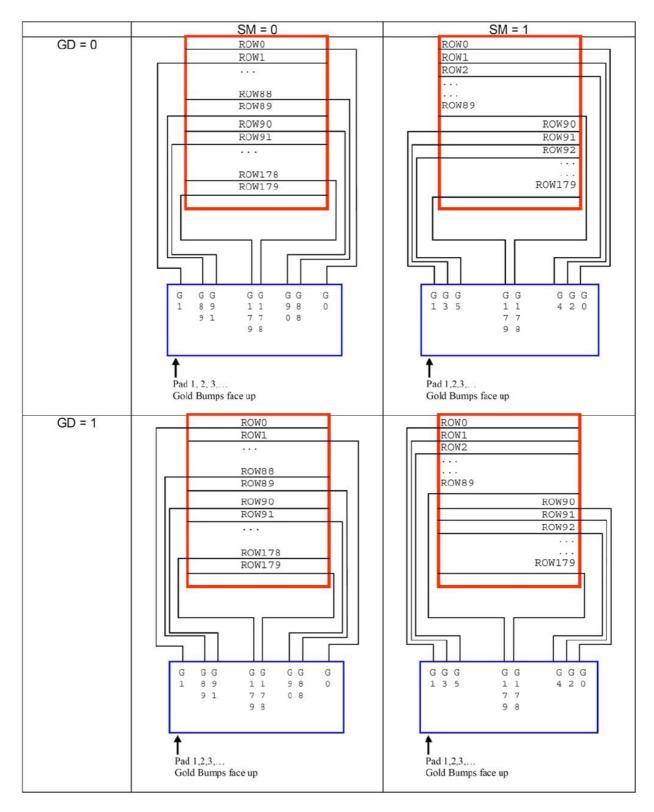


Figure: Output pin assignment on different Scan Mode Setting

# 6.2 Gate Scan Start Position (0Fh)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	SCN7	SCN6	SCN5	SCN4	SCN3	SCN2	SCN1	SCN0
PC	)R	0	0	0	0	0	0	0	0

This command is to set Gate Start Position for determining the starting gate of display RAM by selecting a value from 0 to 179. Figure 8-2 shows an example using this command of this command when MUX ratio = 180 and MUX ratio = 90. "ROW" means the graphic display data RAM row.

	MUX ratio (01h) = 179	MUX ratio (01h) = 89	MUX ratio (01h) = 89
GATE Pin	Gate Start Position (0Fh) = 0	Gate Start Position (0Fh) = 0	Gate Start Position (0Fh) = 45
G0	ROW0	ROW0	-
G1	ROW1	ROW1	-
G2	ROW2	ROW2	-
G3	ROW3	ROW3	-
:	:	:	:
:	:	:	:
G43	:	:	-
G44	:	:	-
G45	:	:	ROW45
G46	:	:	ROW46
:	:	:	:
:	:	:	:
G88	ROW88	ROW88	:
G89	ROW89	ROW89	:
G90	ROW90	-	:
G91	ROW91	-	:
:	:	:	:
:	:	:	:
G133	:	:	ROW133
G134	:	:	ROW134
G135	:	:	-
G136	•	•	-
:	•	•	:
:	•	•	:
G176	ROW176	-	-
G177	ROW177	-	-
G178	ROW178	-	-
G179	ROW179	-	-

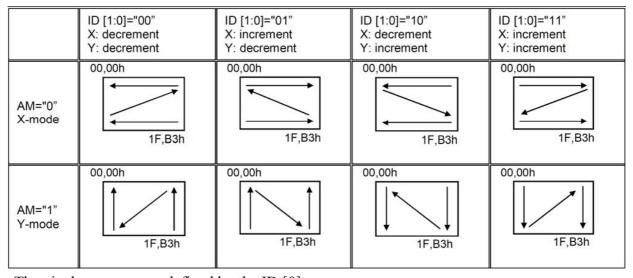
# 6.3 Data Entry Mode Setting (11h)

This command has multiple configurations and each bit setting is described as follows:

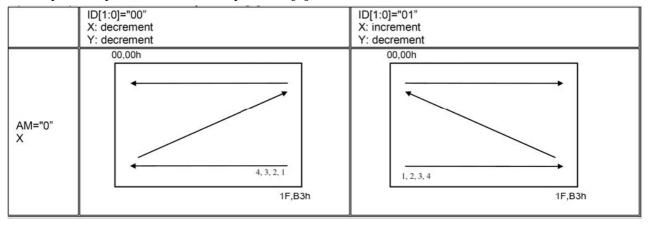
R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1						AM	ID1	ID0
PC	)R	0	0	0	0	0	0	0	0

**ID[1:0]:** The address counter is automatically incremented by 1, after data are written to the RAM when ID[1:0] = "1". The address counter is automatically decremented by 1, after data are written to the RAM when ID[1:0] = "0". The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. The direction of the address when data are written to the RAM is set with AM bits.

**AM:** Set the direction in which the address counter is updated automatically after data are written to the RAM. When AM = "0", the address counter is updated in the X direction. When AM = "1", the address counter is updated in the Y direction. When window addresses are selected, data are written to the RAM area specified by the window addresses in the manner specified with ID1-0 and AM bits.



The pixel sequence are defined by the ID [0]



The totally image display style setting is shown as below table:

REG#	Style 1	Style 2	Style 3	Style 4
11h	0x03	0x02	0x01	0x00
	0x00	0x11	0x00	0x11
44h	0x11	0x00	0x11	0x00
451	0x00	0x00	0xAB	.0xAB
45h	0xAB	0xAB	0x00	0x00
4Eh	0x00	0x11	0x00	0x11
4Fh	0x00	0x00	0xAB	0xAB
Image display sample	S0 S71 G0 DISHTYA	S0 S71 G0 DISPLAY G171	S0 S71 G0 AV365IQ	S0 S71 G0 YA-4800
Display data distilling format setting	2 Scanning direction: ve  3 Image display mode: F  DISPLAY  4 The max. width: 172 The max. height: 72 5 Output gray: 4 gray	rtical scan mode		

**POR** 

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1				XSA4	XSA3	XSA2	XSA1	XSA0
PC	)R	0	0	0	0	0	0	0	0
117	1				VEA4	VEA2	VEAC	VEA1	VEAO

#### 6.4 Set RAM X - Address Start / End Position (44h)

**XSA[4:0]/XEA[4:0]:** Specify the start/end positions of the window address in the X direction by 4 times address unit. Data are written to the RAM within the area determined by the addresses specified by XSA [4:0] and XEA [4:0]. These addresses must be set before the RAM write. It allows on XEA [4:0]  $\leq$  XSA [4:0]. The settings follow the condition on  $00h \leq$  XSA [4:0], XEA [4:0]  $\leq$  1Fh. The windows is followed by the control setting of Data Entry Setting (R11h).

## 6.5 Set RAM Y - Address Start / End Position (45h)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	YSA7	YSA6	YSA5	YSA4	YSA3	YSA2	YSA1	YSA0
PC	)R	0	0	0	0	0	0	0	0
W	1	YEA7	YEA6	YEA5	YEA4	YEA3	YEA2	YEA1	YEA0
PC	)R	1	1	0	1	0	0	1	1

**YSA[7:0]/YEA[7:0]:** Specify the start/end positions of the window address in the Y direction by an address unit. Data are written to the RAM within the area determined by the addresses specified by YSA [7:0] and YEA [7:0]. These addresses must be set before the RAM write. It allows YEA [7:0]  $\leq$  YSA [7:0]. The settings follow the condition on  $00h \leq$  YSA [7:0], YEA [7:0]  $\leq$  B3h. The windows is followed by the control setting of Data Entry Setting (R11h).

#### 6.6 Set RAM Address Counter (4Eh-4Fh)

REG#	R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
4Eh	W	1				XAD4	XAD3	XAD2	XAD1	XAD0
4EII	POR		0	0	0	0	0	0	0	0
4Fh	W	1	YAD7	YAD6	YAD5	YAD4	YAD3	YAD2	YAD1	YAD0
4611	PC	)R	0	0	0	0	0	0	0	0

**XAD[4:0]:** Make initial settings for the RAM X address in the address counter (AC).

**YAD[7:0]:** Make initial settings for the RAM Y address in the address counter (AC).

After RAM data are written, the address counter is automatically updated according to the settings with AM, I/D bits and setting for a new RAM address is not required in the address counter. Therefore, data are written consecutively without setting an address. The address counter is not automatically updated when data are read out from the RAM. RAM address setting cannot be made

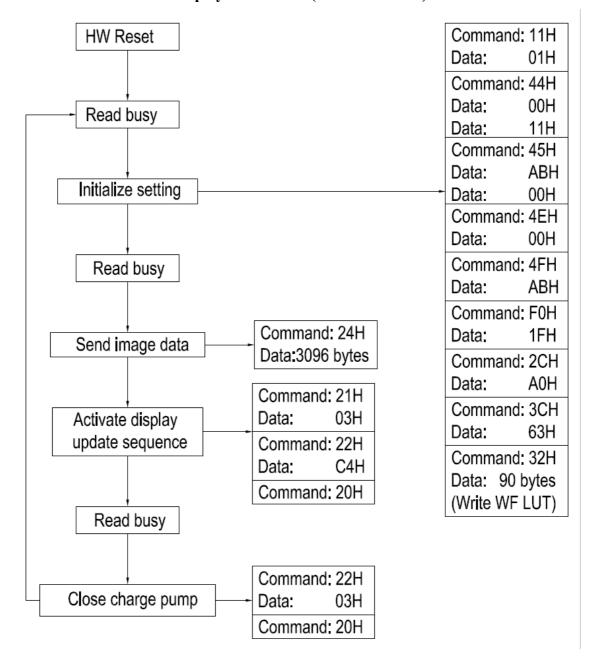
automatically updated when data are read out from the RAM. RAM address setting cannot be made during the standby mode. The address setting should be made within the area designated with window addresses which is controlled by the Data Entry Setting (R11h) {AD, ID[1:0]}; RAM Address XStart / XEnd Position (R44h) and RAM Address Ystart / Yend Position (R45h). Otherwise undesirable image will be displayed on the Panel.

# 7. Typical Operating Sequence

# 7.1 Normal Display

Sequence	Action by	Command	Action description	Remark
1	User	-	Power on (VCI supply)	
2	User	-	HW Reset	
	IC		After HW reset, the IC will have Registers load with POR value Ready for command input VCOM register loaded with OTP value IC enter idle mode	
3		-	Send initial code to driver including setting of	
	User	C 01	Command: Panel configuration (MUX, Source gate scanning direction)	
	User	C 03	Command: VGH / VGL voltage	
	User	C 04	Command: VSH / VSL voltage	
	User	C 3A	Command: Set dummy line pulse period	
	User	C 3B	Command: Set Gate line width	
	User	C 3C	Command: Select Border waveform	
4		-	Data operations	
	User	C 11	Command: Data Entry mode	
	User	C 44	Command: X RAM address start /end	
	User	C 45	Command: Y RAM address start /end	
	User	C 4E	Command: RAM X address counter	
	User	C 4F	Command: RAM Y address counter	
	User	C 24	Command: write display data to RAM	
			Ram Content for Display	
5	User	C F0 D 1F	Command: Set Internal Feedback Selection	
6	User	C 20	Command: Display update	
	IC	-	Booster and regulators turn on	
	IC	-	Load temperature register with sensor reading	
	IC	-	Load LUT register with corresponding waveform setting stored in OTP	
	IC	-	Send output waveform according initial update option	
	IC	-	Send output waveform according to data	
	IC	-	Booster and Regulators turn off	
	IC	-	Back to idle mode	
7	User	-	IC power off	

## 7.2 The Normal Flow Chart for Display One Screen (WF LUT Mode)



# 7.3 Waveform Setting OTP Program

Sequence	Action by	Command	Action description	Remark
1	User	-	Power on (VCI supply)	
2	User	-	Power on (VPP supply)	
3	User	-	HW Reset	
4	User	C 2D	Check whether the IC status and determine whether "default" or "spare" OTP should be used	
5	User		If the IC had been OTP twice (both default and spare had been used up). The operation should stop	
6	User	C 37	Proceed OTP sequence. Command: Indicate which OTP location to be use (default or spare)	OTP selection register
	User	C 22 D 80 C 20	Command: CLKEN=1	
	User	-	Wait BUSY = L	
7	User	C 36	Program OTP selection register	
	User	-	Wait BUSY = L	
8	User	C 24	Write corresponding data into RAM	
			Following specific format	
			Write into RAM	
			Full LUT (11 entries + Temperature range) must be written at the same time	
	User	C 4E D 00 C 4F D 00	Command: Initial Ram address counter	
9	User	C 30	Waveform Setting OTP programming	
	IC	-	BUSY pin pull H	
	IC	-	Check the OTP Selection	
	IC	-	IC control OTP programming time, and transfer data to selected OTP	
	IC	-	BUSY pin pull L	
	User	-	Wait BUSY = L	
10	User	C 22 D 01 C 20	Command: CLKEN=0	
	User	-	Wait BUSY = L	
11	User		IC power off	

# 7.4 VCOM OTP Program

Sequence	БУ		Remark			
1			Power on (VCI and VPP supply)			
2	User	-	HW Reset			
3	User	C 2D	Check whether the IC status and determine whether "default" or "spare" OTP should be used			
4	User		If the IC had been OTP twice (both default and spare had been used up). The operation should stop			
5				OTP selection register		
	User	C 22 D 80 C 20	Command: CLKEN=1			
	User	-	Wait until BUSY = L			
6	User	C 36	Program OTP selection register			
	User	-	Wait until BUSY = L			
	User	-	Power OFF (VPP supply)			
7	Send initial code to driver including setting of (or lea as POR)					
	User	C 01	Command: Panel configuration (MUX, Source, Gate scanning direction)			
	User	C 03	Command: VGH / VGL voltage			
	User	C 04	Command: VSH / VSL voltage	VCOM		
	User	C 3A	Command: Set dummy line pulse period sensi			
	User	C F0 D 1F	Command: Set Internal Feedback Selection	should have same setting		
	User	C 32	VCOM sense required full set of LUT for operation, USER required writing LUT in register 32h	during application		
		-	LUT parameter	application		
	User	C 22 D 40 C 20	Command: Booster on and High voltage ready			
	User	-	Wait until BUSY = L			
8	User	C 28	Command: Enter VCOM sensing mode			
	IC	-	VCOM pin in sensing mode			
			All Source cell have VSS output			
	IC		All Gate scanning continuously			
	IC	-	Wait for 10s	According to		
	IC	-	Detect VCOM voltage and store in register	R29h		
	IC	-	All Gate Stop Scanning.			
	User	-	Wait until BUSY = L			

9	User	C 22 D 02 C 20	Command: Booster and High voltage disable
	User	-	Wait until BUSY = L
	User	-	Power On (VPP supply)
10	User	C 2A	Command: VCOM OTP program
	User	-	Wait until BUSY = L
11	User	C 22 D 01 C 20	Command: CLKEN=0
	User	-	Wait until BUSY = L
12	User	-	IC power off (VCI and VPP Supply)

# OTP Selection bit:

Set on R37h, and read from R2Dh, A[7:6] used for VCOM and A[5:4] used for OTP

A[7:6] / [5:4]	Description	
00	It indicates fresh device, OTP read and program would be made on Default OTP set. User required setting and programming the bits into 01.	
01	It indicates default OTP programmed device, OTP read would be made on Default OTP set. User require setting and programming the bits into 11.	
	It indicates SPARE OTP programmed device, only OTP read would be made on SPARE OTP set.	
11	User should stop the OTP programming if 11 is found at OTP checking stage.	

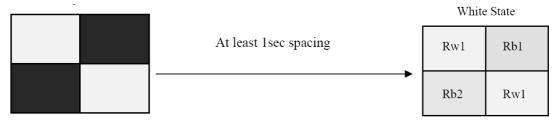
#### 8. Optical characteristics

Measurements are made with that the illumination is under an angle of 45 degrees, the detection is perpendicular unless otherwise specified.

Symbol	Parameter	Conditions	Values			Units	Notes
Symbol			Min.	Тур.	Max	Units	Tioles
R	White Reflectivity	White	30	35	-	%	11-1
CR	Contrast Ratio		7:1	8:1	-	-	11-2
Tupdate	Image update time	at 25 °C	-	1800	-	ms	-
Ghosting	Image sticking	_	-2.0	1.0	2.0	-	11-3

Notes: 1. Luminance meter: Eye-One Pro Spectrophotometer.

- 2. CR=Surface Reflectance with all white pixel/Surface Reflectance with all black pixels.
- 3. Ghosting Testing:
- 3-1. Testing Pattern



- 3-2. Refresh process: Init ---- GC White ---- 4 checkerboard Pattern GC ---- GC White.
- 3-3. Measuring the reflectance of all 4 checkerboard areas when final white state by Eye-one device.
- 3-4. Rw: reflectance of area transited from white state Rb: reflectance of area transited from dark (black) state
- 3-5. Calculating averages of WS-to-WS and DS-to-WS transitions: Rw(ave)=(Rw1+Rw2)/2, Rb(ave)=(Rb1+Rb2)/2, G=Rw(ave)-Rb(ave).

# 9 Appearance Inspection Standard

# 9.1 Major Defects

<b>Defect Type</b>	Description			
No display	Not able to display any image			
Line defect	Complete line(s) missing or unusual appear when display			
Abnormal display	Unusual pattern or function when display			

#### 9.2 Minor Defects

Environmental condition		Temperature / Humidity	Environmental iliumination	Distance	Time	Angle	
		20°C -25°C 40%RH-55%RH	700-1000Lux	200-300mm	20 sec	Up/down 30 degree (Rotation)	
	NO.	Defect type	Check	Acceptable	A Zone	B Zone	
		Spot (B/W spot, dent in glass or protection sheet, foreign mat. Swell. Dot defect) (unwork)	By eye and gauge	D ≤ 0.2mm	Ignore		
	1			0.2mm <d≦0.3mm< td=""><td>≤4 (two spot spacing greater than 20mm)</td><td colspan="2"></td></d≦0.3mm<>	≤4 (two spot spacing greater than 20mm)		
				$0.3 \text{mm} < D \le 0.35 \text{mm}$	N ≦ 1		
appearance Inspection				D>0.35mm	NG		
standard	2	Scratch or line defect ( scratch or foreign mat. Protection sheet ) (unwork)	By eye and gauge	$L \leq 0.5 \text{mm} \& W \leq 0.2 \text{mm}$	Ignore	OK	
				0.5 mm< L ≤ 3mm & 0.2mm <w≤0.3mm< td=""><td>≤2 (the center of two line spacing greater than 30mm)</td><td></td></w≤0.3mm<>	≤2 (the center of two line spacing greater than 30mm)		
				L>3.0mm or W>0.3mm	NG		
	3	Air bubble	By eye and gauge	$D1/D2 \le 0.2$ mm	Ignore		
				$0.2$ mm $<$ D $1/D2 \le 0.5$ mm	N ≦ 3		
				D1/D2>0.5mm	NG		
	4	Stab	By eye	No hurt PET	NG		

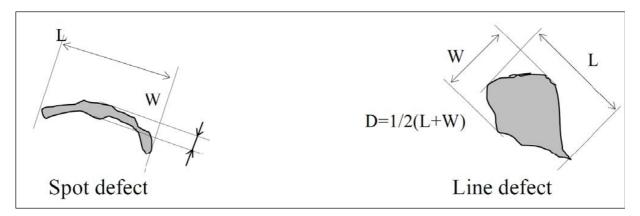
Note: 1. Spot size is based on microscope  $10x\sim100x$ 

2. Spot define: That only can be seen under WS, BS or GS defects.

3. A Zone: Active area(defined in specification)

B Zone: Border area from A Zone edge

# 9.3 Spot and Line Defect Test and Calculation



# 9.4 Spot and Line Test Standard

When  $L \leq 0.5$ mm, test as point.

When L<4W, test as point.

# 9.5 Air Bubble Defect Test and Calculation



#### 10. Handling, safety and environmental requirements

#### WARNING

The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

#### **CAUTION**

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components. Disassembling the display module can cause permanent damage and invalidate the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

Data sheet status	
Product specification	The data sheet contains final product specifications.
T ' '4' 1	

#### Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and dose not form part of the specification.

# 11. Reliability test

	Test	Condition	method	Remark
1	High-Temperature Operation	$T = 50^{\circ}C,30\%$ for 240 hrs	IEC 60 068-2-2Bp	
2	Low-Temperature Operation	T = 0°C for 240 hrs	IEC 60 068-2-2Ab	
3	High-Temperature Storage	$T = +70^{\circ}$ C, 23% for 240 hrs Test in white pattern	IEC 60 068-2-2Bp	
4	Low-Temperature Storage	T = -25°C for 240 hrs Test in white pattern	IEC 60 068-2-2Ab	
5	High Temperature, High-Humidity Operation	T=+40°C,RH=90%for168hrs	IEC 60 068-2-3CA	
6	High Temperature, High-Humidity Storage	T=+60°C,RH=80%for240hrs Test in white pattern	IEC 60 068-2-3CA	
7	Temperature Cycle	-25°C → +70°C,100 cycles 30mins 30mins Test in white pattern	IEC 60 068-2-14	
8	UV exposure Resistance	765 W/m2 for 1688 hrs,40°C	IEC 60 068-2-5 Sa	
9	Electrostatic Effect (non-operating)	Machine mode +/- 250V, 0Ω,200pF	IEC62179, IEC62180	
10	Package Vibration	1.04G,Frequency: 10~500Hz Direction: X,Y,Z Duration:1hours in each direction	Full packed for shipment	
11	Package Drop Impact	Drop from height of 122 cm on Concrete surface Drop sequence:1 corner, 3edges, 6face One drop for each.	Full packed for shipment	

Actual EMC level to be measured on customer application.

Note: The protective film must be removed before temperature test.

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Electronic Paper Displays - ePaper category:

Click to view products by Display Elektronik manufacturer:

Other Similar products are found below:

PIM534 E2741JS0B2 16565 17779 DEE 172072A-W 13187 13353 14410 14597 19406 19408 14986 15084 13186 18401 18057 EA

EPA20-A DEE 600800A-W DFR0369 10628 12561 12563 12672 12915 12955 12956 3625 4086 4098 4195 4196 4197 4243 4262

4777 4778 4814 000026 000041 DEE 400300A2-W DFR0835 DFR0837 DEE 800480A-W EA ELABEL20-A EA EPA43-A EA EPA60-A

28084 E2154CS0C1 E2154JS0C1 E2260CS021